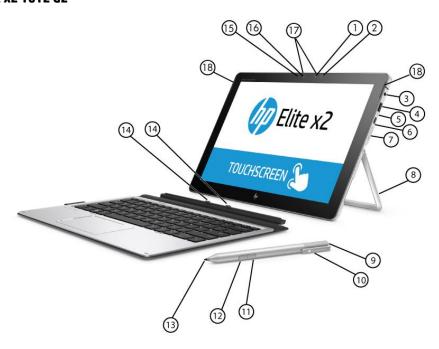
## HP Elite x2 1012 G2



- 1. Infrared camera
- 2. Infrared camera light
- 3. Audio-out/Audio-in combo jack
- 4. USB-A 3.0
- 5. Power LED
- 6. USB Type-C™ with Thunderbolt
- 7. Micro SIM Card Slot\*
- 8. Kickstand
- 9. Application Launch Button (Default OneNote)

- 10. Clip
- 11. Select (Programmable Function Button)
- 12. Erase (Programmable Function Button)
- 13. Tip
- 14. Keyboard guide pins
- 15. Webcam light
- 16. Webcam
- 17. Microphones
- 18. Front-firing speakers

<sup>\*</sup>only available on configurations with WWAN enabled



- 1. Power
- 2. Volume Up/Volume down
- 3. Micro SD Memory Card Slot
- 4. Security Cable Slot
- 5. Pen Lanyard Slots





- 1. Camera
- 2. Camera Flash

3. Fingerprint Sensor (optional)



## HP Elite x2 1012 G2 Collaboration Keyboard

- 1. ClickPad
- 2. Pen Holder
- 3. Guide Pins

## Collaboration Keys:

- 4. Present
- 5. Call answer/initiate
- 6. Call end

## **Collaboration Keys Detail**



- 1. Present
- 2. Call answer/initiate
- 3. Call end
- 4. Delete



## HP Elite x2 1012 G1 Advanced Keyboard

- 1. ClickPad/NFC Area
- 2. Smart card Slot
- 3. Guide Pins



## At A Glance

- Designed for excellent mobility, this stylish and thin 2-in-1 design is built to the standards of Elite durability
- The quiet design and up to 10 hours and 15 minutes of battery life¹ lets you work, surf, and connect with colleagues
- Windows 10 versions
- 7<sup>th</sup> Generation Intel® Core™ (U-series) processors, some with vPro™ support²
- 12.3" diagonal ultra-slim LED-backlit better than QHD (2736 x 1824) Multi-Touch Display
- Solid State Drives up to 512GB including FIPS 140.2 (CIS only); OPAL 2 drives support up to 256GB PCLe NVMe drives support up to 1024GB
- · Weight starting at 810g for Tablet
- Height starting at 8.05mm for Tablet
- Passed MIL-STD 810G testing:
  - MIL-STD is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. MIL-STD test results are not a guarantee of future performance under these test conditions.
     Damage from drops requires separately purchase Accidental Damage Protection HP Care Pack.
- Audio by Bang & Olufsen
- Optional IR camera
- Dual microphone array with HP Advanced Noise Reduction Software
- Front and Back facing camera and webcam
- Supports a broad range of wireless broadband and Wi-Fi options for connectivity on the go
- Optimized security using industry standard technologies such as TPM2.0, optional integrated fingerprint reader and an
  optional smart card reader in the optional Advanced keyboard
- Passed EN 60601-1-2:2007 and IEC 60601-1-2:2014 tests
- ENERGY STAR® certified. EPEAT® Gold registered where applicable/supported. Registration may vary by country. See
  www.epeat.net for registration status by country.
- Protect your device and data using the latest HP security technology solutions: HP Sure Start, HP BIOSphere and HP Client Security.
- Standard commercial 1 year limited warranty with extended service available with optional HP Care Packs.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

<sup>1</sup> Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

 $^{2}\,v\text{Pro}^{\text{\tiny{TM}}}$  support not available on all configurations.



#### **PRODUCT NAME**

HP Flite x2 1012 G2

## **OPERATING SYSTEM**

Preinstalled Windows 10 Pro 641

Windows 10 Pro 64 (National Academic License)<sup>2</sup>

Windows 10 Home 641

Windows 10 Home Single Language 641

Web-only Support Windows 10 Enterprise 64

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

## PROCESSOR\*

#### 7th Generation Intel® Core™ i3, i5 and i7 Processors:

Intel® Core™ i3-7100U with Intel® HD Graphics 620 (2.4 GHz, 3 MB cache, 2 cores)

Intel® Core™ i5-7200U with Intel® HD Graphics 620 (2.5 GHz, up to 3.1 GHz with Intel® Turbo Boost Technology\*\*, 3 MB cache, 2 cores)

Intel® Core™ i5-7300U with Intel® HD Graphics 620

(2.6 GHz, up to 3.5 GHz with Intel® Turbo Boost Technology\*\*, 3 MB cache, 2 cores), vPro™ Support

Intel® Core™ i7-7600U with Intel® HD Graphics 620

(2.8 GHz, up to 3.9 GHz with Intel® Turbo Boost Technology\*\*, 4 MB cache, 2 cores), vPro™ Support

\* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology.. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance.
\*\* Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See <a href="http://www.intel.com/technology/turboboost">http://www.intel.com/technology/turboboost</a> for more information.

## **CHIPSET**

Integrated with processor



**HP Elite x2 1012 G2** 

## **Technical Specifications**

#### **GRAPHICS**

Intel® HD Graphics 620

#### **DISPLAY**

#### Internal

#### **Touch screen**

12.3" diagonal BrightView LED-backlit better than QHD\* UWVA eDP 1.3 Ultra-slim (2736 x 1824) Touch screen Chemically-strengthened Corning® Gorilla® Glass 4 top cover directly bonded to display

Refresh Rate 60 Hz

Brightness 450 nits (maximum)

**Pixel Resolution** Format 2736 x 1824 (better than QHD)

Configuration RGB Stripe

 Interface
 eDP 1.3

 LCD Mode
 IPS

 PPI
 268 ppi

Viewing Angle UWVA 85/85/85 (Left/Right/Down/Up)

Color Gamut 72%

External

24-bit + 8 bit alpha channel (standard)

Up to 30-bit per pixel color depth (Wide Color Gamut)

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

## STORAGE AND DRIVES

## Internal Storage\* - supports M.2 SSD SS 2280

- 128 GB SATA-3 SS VALUE SSD
- 256GB 2280 M2 PCIe-3x4 SS NVMe TLC
- 256GB 2280 M2 SATA-3 Self Encrypted OPAL2 TLC
- 256GB 2280 PCIe NVMe Value
- 360GB 2280 PCIe-3x4 NVMe TLC
- 512GB 2280 M2 PCIe-3x4 SS NVMe TLC
- 512GB 2280 PCIe NVMe Value
- 512GB 2280 M2 SATA-3 Three Layer Cell Federal Information Processing Standard (FIPS 140.2 available via CIS only)
- 1024 GB 2280 PCIe-3x4 NVMe TLC

#### **Expansion Storage**

Micro SD Media Reader Slot - Supports microSD, microSDHC, microSDXC, supporting expansion up to 2TB



<sup>\*</sup> HD content required to view HD images.

<sup>\*</sup> For SSD's, GB=1 billion bytes. TB=1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) of system disk is reserved for system recovery software.

#### **MEMORY**

LPDDR3-1866 (Transfer rates up to 1866 MT/s) Supports Dual Channel Memory Soldered Down

#### Standard

4 GB Total System Memory 8 GB Total System Memory

#### Maximum

Up to 16 GB

## **NETWORKING/COMMUNICATIONS**

#### Wireless

Support for a broad range of secure, integrated wireless LAN/Bluetooth and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a factory-only configurable feature only. Standalone GPS is also available (factory configurable only) and is supported via combo card

#### Wireless WAN (WWAN)\*

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module HP lt4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module HP hs3210 HSPA+ Mobile Broadband Module

#### Wireless LAN (WLAN)\*\*

Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo (vPro) Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo (non-vPro)

#### Standalone GPS\*\*\*\*

HP Graff GNSS Module

- \* WWAN is an optional feature and requires factory configuration. WWAN connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.
- \*\*Wireless access point and Internet service is required and is not included. Availability of public wireless access points limited.
- \*\*\*Standalone GPS is an optional feature and requires factory configuration. GPS and WWAN are mutually exclusive.



## **AUDIO/MULTIMEDIA**

#### Audio

Audio by Bang & Olufsen
Dual speakers (front facing)
Dual microphone array with echo cancellation, noise suppression
Headphone line-out and microphone-in (combo)
HP Advanced Noise Reduction Software

#### Camera – Front

Integrated 5 MP (1080p)

- 1080p format for video
- 5 MP for still capture
- Supports videoconferencing\* and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1920x1080 resolution (1080p) and up to 30 fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing\*
- Improved low light sensitivity
- Improved dynamic range

#### Camera – Back

Integrated 8 MP with flash (1080p)

- 1080p format for video
- 8 MP for still capture
- Supports videoconferencing\* and still image capture
- High quality auto focus lens
- Video capture at various resolutions up to 1920x1080 resolution (1080p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing\*
- Improved low light sensitivity
- Improved dynamic range

#### IR Camera

 $Integrated VGA\ IR\ camera\ w/\ IR\ LED\ emitters\ that\ meets\ Microsoft\ Hello\ face\ recognition\ certification\ for\ secure\ authentication.$ 

\* Internet access required.

## **ACTIVE PEN**

## HP Active Pen with Bluetooth® App Launch

Pen Technology Wacom AES
Digitizer N/A, shared with touch

 Dimensions
 147.4 x 9.5 mm

 Weight
 17.5 q

Power AAAA battery and 319 coin cell x2

System Requirements Windows 10
Tip Diameter 1 mm

**Pen Tips** Three extra elastomer pen tips for replacement

Pressure Sensitivity Yes (2048 levels)

(Y/N)

Buttons (Y/N) Yes, 3
Resolution 2540 ppi
Report rate 133hz
Hover Capability (Y/N) Yes



Hover Height (mm) 10mm+ Palm Rejection (Y/N) Yes

Tilt Angle (Y/N) Battery Life Based on >60 degrees from vertical

Continuous Usage

7.5 month+

## **OPTIONAL KEYBOARDS**

#### Optional HP Elite x2 1012 G2 Collaboration Keyboard\*

Kit contents HP Elite x2 1012 G2 Collaboration Keyboard and documentation

Weight .78 lb (353 g)

## Optional HP Elite x2 1012 G1 Advanced Keyboard\*

**Kit contents** HP Elite x2 1012 G1 Advanced Keyboard and documentation

**Key Features** Smart card reader FIPS-201 compliant.

Security - Near Field Communications (NFC) Module

Weight .992 lb (450 g)

\*Sold as an optional feature

## Keyboard Features (common to both Collaboration and Advanced Keyboards)

- Backlit
- HP DuraKeys
- 1.3mm key travel
- 18.4mm pitch
- ClickPad™ (91 x 51 mm) with image sensor, multi-touch gestures enabled, on/off function and LED indicator
- 165° max opening angle
- Docking connector to tablet
- Wipeable back cover
- Full size 81/82-key island-style backlit keyboard with full row of function keys and LED indicators

## ClickPad

Glass with chemical etched surface

Supports 2-way scroll Taps enabled as default

Gestures enabled by default - 2 Finger Scrolling, 2 Finger Zoom (Pinch)

## **Keyboard Features (Collaboration Keyboard only)**

F1 – Display Switching

F2 - Blank

F3 - Brightness Down

F4 - Brightness Up F5 - Speaker Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Backlight Toggle

F10 – Number Lock

F11 – Wireless On/Off

F12 – Calendar



Dedicated Skype for Business keys:

Present Call answer/initiate Call end Delete

#### Keyboard Features (Advanced Keyboard only)

**Function Keys** 

F1 - Blank F2 - Blank F3 - Sleep

F4 - Display Switching F5 – Speaker Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Brightness Down F10 - Brightness Up

F11 - Backlight Toggle F12 - Wireless On/Off

## **SOFTWARE AND SECURITY**

## **Preinstalled Software with Windows Operating System**

HP BIOSphere Gen31 HP Sure Start Gen3<sup>2</sup> HP DriveLock | HP Automatic DriveLock **BIOS Update via Network** Master Boot Record Security Power On Authentication Secure Erase<sup>3</sup> Absolute Persistence Module<sup>4</sup> **Pre-boot Authentication** 

## Communication / Connectivity

HP Mobile Connect Pro⁵ Native Miracast Support<sup>6</sup> HP LAN-WLAN Protection
HP MAC Address Manager (select models only) **HP SureConnect HP Velocity** 

**HP Value Add Software** HP ePrint Driver + JetAdvantage<sup>7</sup> **HP Hotkey Support - CMIT** HP Jumpstart **HP Support Assistant** 



**HP Noise Cancellation Software** 

#### **Microsoft Products**

Buy Office Bing Search Skype<sup>8</sup>

#### Manageability

HP Driver Packs<sup>9</sup>
HP SoftPaq Download Manager (SDM)
HP System Software Manager (SSM)<sup>9</sup>
HP BIOS Config Utility (BCU)<sup>9</sup>
HP Client Catalog<sup>9</sup>
HP MIK for Microsoft SCCM<sup>9</sup>
LANDESK Management<sup>10</sup>

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

#### **Client Security Software**

**HP Client Security** 

- HP Security Manager (including Credential Manager and Password Manager)
- HP Drive Lock
- HP Fingerprint Sensor
- HP Password Manager
- Absolute Persistence Module
- Power On Authentication
- Microsoft Defender<sup>12</sup>
- HP Workwise<sup>13</sup>

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

#### **Security Hardware**

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified)

HP Fingerprint Reader (selectd models)

Integrated VGA IR camera with IR LED emitters that meets Microsoft Hello face recognition certification for secure authentication (select models)

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. BIOSphere Gen3 requires Intel® or AMD® 7th generation processors.
- 2. Available on HP Elite products equipped with Intel® 7th generation processors as well as the HP Pro x2 612 G2.
- 3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to www.hp.com/go/mobileconnect
- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players



that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast

- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter).
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. Subscription required.
- 11. Opt in and internet connection required for updates.

HP Workwise smartphone app is available as a free download on the App Store and Google Play. See requirements at http://www.hp.com/go/workwise

#### **POWER**

#### **Power Supply**

HP 45 W USB Type-C<sup>™</sup> AC adapter HP 65 W USB Type-C<sup>™</sup> AC adapter

- USB Type-C<sup>™</sup> DC integrated cord (1.8m)
- AC Power cord (1m)
- AC Adapter Weight: 245g +/- 10g

#### Tablet – Battery

4-cell Long Life Polymer 47Whr (3055mAhr/cell)

- Voltage 7.7 V
- Supports HP Fast Battery Charging\*

#### **Battery Life\*\***

Windows 10 battery time:

Up to 10 hours and 15 minutes \*

- \* Units enabled with 65w adapters or higher can support fast charging of the battery from 0-50% in 30 minutes while the system is off
- \*\*Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

## **WEIGHTS & DIMENSIONS**

#### Weight\*

## Tablet only

Starting at 1.77 lbs (803 g)

### **Tablet with Travel Keyboard**

2.55 lbs (1156 g)

#### **Tablet with Advanced Keyboard**

2.94 lbs (1333 g)

Dimensions - (w x d x h)\*

#### Tablet

11.8 x 8.4 x 0.3 in (300 x 213.85 x 8.05 mm)



#### **Tablet with Travel Keyboard**

11.8 x 8.63 x 0.53 in (300 x 219.3 x 13.55 mm)

#### **Tablet with Advanced Keyboard**

11.8 x 8.6 x 0.6 in (300 x 219.3 x 16.65 mm)

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components.

\*Values are preliminary and may be updated before product launch.

#### PORTS/SLOTS

## Tablet

#### **Ports**

1 USB Type-C™, supporting USB 3.1 (supports Thunderbolt™ 3)

1 USB Type-A, supporting USB 3.0

1 Headphone /microphone combo

NOTE: For optimal performance, the HP x2 1012 G2 should charge from a USB Power Delivery, v2 compatible adapter or power source that offers 12V @ 3A.

#### Slots

1 Micro SIM drawer (optional)

1 Micro SD Media Reader Drawer -supports microSD, microSDHC, microSDXC

1 Lock slot

## **Advanced Keyboard**

**Ports** 

## Slots

1 Smart card reader

## **SENSORS**

Accelerometer

Magnetometer

Gyro

ALS (Ambient Light Sensor)

Proximity (SAR for WWAN)

Hall Sensor

#### **SERVICE AND SUPPORT**

HP Services offers 3-year, 1-year and 90 day limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.



# QuickSpecs

**HP Elite x2 1012 G2** 

## **Technical Specifications**

Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc.



## **SYSTEM UNIT**

Stand-Alone Power Requirements (AC Power) Voltage

**Nominal Operating** 

**Nominal Operating** 

Amperage

Average Operating Power 7.21 W (non-charging)

**Max Operating Power** 

Temperature Operating 32° to 95° F (0° to 35° C) (not writing optical)

41° to 95° F (5° to 35° C) (writing optical)

**Relative Humidity** 

**Non-operating** -4° to 140° F (-20° to 60° C) Operating 10% to 90%, non-condensing

**Non-operating** 

5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

**Non-operating** 240 G, 2 ms, half-sine

15 V

4.33A

**Random Vibration** 

1.043 grms Operating **Non-operating** 3.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m)

**Non-operating** 

-50 to 40,000 ft (-15.24 to 12,192 m)

## **ENVIRONMENTAL & INDUSTRY**

Environmental Data HP Elite x2 1012 G2

Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:  • IT ECO declaration  • US ENERGY STAR®  • US Federal Energy Management Program (FEMP)  • EPEAT <sup>®</sup> Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword <i>generator</i> on HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options.  • TCO or TCO Certified Edge				
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".				
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
	Normal Operation (Sort idle)	6.36 W	6.49 W	6.35 W		
	Normal Operation (Long idle)	2.83 W	2.46 W	2.58 W		
	Sleep	0.49 W	0.52 W	0.48 W		



Off	0.40 W	0.43	W	0.40 W
	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz	230VAC	. 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	21 BTU/hr	22 BT	•	21 BTU/hr
Normal Operation (Long idle)	10 BTU/hr	8 BTU	J/hr	9 BTU/hr
Sleep	2 BTU/hr	2 BTL	J/hr	2 BTU/hr
Off	1 BTU/hr	1 BTU	J/hr	1 BTU/hr
	*NOTE: Heat dissipation is calculated based on the measured watts, assuming service level is attained for one hour.		asured watts, assuming the	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L <sub>WAd</sub> , bels)			Sound Pressure (L <sub>pAm</sub> , decibels)
Typically Configured – Idle	2.6 15		15	
Fixed Disk – Random writes	2.8 18		18	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:  3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD??  Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.  This battery(s) in this product comply with EU Directive 2006/66/EC  Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			n the product may include:
Batteries				
	Battery description: CR2032 (coin cell) Battery type: Lithium Battery description: 6-cell high capacity Lithium-Ion battery (optional 8 capacity Lithium-Ion bat		attery (optional 8 cell	



Additional Information	This product is in compliance with the Restrictions of Hazardo				
Additional mile mation	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and</li> </ul>				
	Electronic Equipment (WEEE) Directive – 2002/96/EC.  This product is in compliance with California Proposition 65 (				
		s product is in compliance with California Proposition fornia; Safe Drinking Water and Toxic Enforcement <i>I</i>			
	<ul> <li>This product is in compliance with the IEEE 1680 (EPEAT) standard at <add gold="" level:=""> level, see www.epeat.net</add></li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.</li> <li>This product contains 0.0% post-consumer recycled plastic (by wt.)</li> </ul>				
		s product is 95.5% recycle-able when properly dispo	sed of at end o		
	life				
Packaging Materials	External:	PAPER/Corrugated	330 (		
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	19 g		
		PLASTIC/Polyethylene low density LDPE	13 g		
		PLASTIC/Polyester - PET	5 g		
	The plastic packaging material contains at least 50% recycled content.				
	The corrugated paper packaging materials contains at le content.		% recycled		
_		does not contain any of the following substances in			
-	regulatory li http://www.	mits (refer to the HP General Specification for the En hp.com/hpinfo/globalcitizenship/environment/pdf/	vironment at		
-	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos	vironment at		
·	regulatory li http://www.	mits (refer to the HP General Specification for the En hp.com/hpinfo/globalcitizenship/environment/pdf/ estos tain Azo Colorants tain Brominated Flame Retardants – may not be use	ovironment at gse.pdf):		
-	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be used	ovironment at gse.pdf):		
-	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be used	ovironment at gse.pdf):		
	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be used	ovironment at gse.pdf):		
	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be userardants in plastics mium orinated Hydrocarbons orinated Paraffins maldehyde	ovironment at gse.pdf):		
	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be userardants in plastics mium orinated Hydrocarbons orinated Paraffins maldehyde ogenated Diphenyl Methanes	ovironment at gse.pdf):		
	regulatory li http://www.	mits (refer to the HP General Specification for the Enhp.com/hpinfo/globalcitizenship/environment/pdf/estos tain Azo Colorants tain Brominated Flame Retardants – may not be user ardants in plastics mium orinated Hydrocarbons orinated Paraffins maldehyde ogenated Diphenyl Methanes d carbonates and sulfates	ovironment at gse.pdf):		
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Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:  Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.  Eliminate the use of ozone-depleting substances (ODS) in packaging materials.  Design packaging materials for ease of disassembly.  Maximize the use of post-consumer recycled content materials in packaging materials.  Use readily recyclable packaging materials such as paper and corrugated materials.  Reduce size and weight of packages to improve transportation fuel efficiency.  Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.	
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.  The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers	
HP, Inc. Corporate Environmental Information	who integrate and re-sell HP equipment.  For more information about HP's commitment to the environment:  Global Citizenship Report  http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label Certifications http://www8.hp.com/us/en/hp-	Field Code Changed
	information/environment/ecolabels.html ISO 14001 certificates:     http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755 842 and     http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf	Field Code Changed Field Code Changed



## STORAGE AND DRIVES

128	GB	SAT	A-3	SS

**VALUE SSD** 

**Drive Weight** 0.02 lb (10 g)

Capacity 128 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0

Performance **Maximum Sequential Read Maximum Sequential Write** 

> 535 MB/s 515 MB/s

**Logical Blocks** 250,069,680

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; DIPM; TRIM; DEVSLP

256GB 2280 M2 PCIe-3x4 Drive Weight SS NVMe TLC

0.02 lb (10 g) Capacity 256 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface PCIe NVMe Gen3X4

Performance **Maximum Sequential Read Maximum Sequential Write** 

> 2600 MB/s 900 MB/s

**Logical Blocks** 500,118,192

32° to 158°F (0° to 70°C) [ambient temp] Operating Temperature

Features ATA Security (Option) TRIM; L1.2

256GB 2280 M2 SATA-3 **Self Encrypted OPAL2** 

TLC

**Drive Weight** 0.02 lb (10 g) Capacity 256 GB Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0

**Maximum Sequential Write** Performance **Maximum Sequential Read** 

> 530 MB/s 515 MB/s

**Logical Blocks** 500.118.192

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature** Features ATA Security; TCG Opal 2.0 DIPM; TRIM; DEVSLP

256GB 2280 PCIe NVMe

Value

**Drive Weight** 0.02 lb (10 g) Capacity 256 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface PCIe NVMe Gen3X4

Performance **Maximum Sequential Read Maximum Sequential Write** 

1700 MB/s 600 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; TCG Opal 2.0; FIPS; TRIM; L1.2

360GB 2280 PCIe-3x4

**NVMe TLC** 

**Drive Weight** 0.02 lb (10 g) Capacity 360GB Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm) PCIe NVMe Gen3X4 Interface

Performance **Maximum Sequential Read Maximum Sequential Write** 

1700 MB/s 600 MB/s

**Logical Blocks** 703,282,608

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security (Option); TRIM; L1.2

512GB 2280 M2 PCle-3x4 Drive Weight

SS NVMe TLC

0.02 lb (10 g) Capacity 512 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface PCIe NVMe Gen3X4

Performance **Maximum Sequential Read Maximum Sequential Write** 

1400 MB/s 2600 MB/s

**Logical Blocks** 1,000,215,216

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature** 

**Features** ATA Security; TRIM; L1.2

512GB 2280 PCIe NVMe

**Drive Weight** 0.02 lb (10 g) Capacity 512 GB Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm) Interface PCIe NVMe Gen3X4

Performance **Maximum Sequential Read Maximum Sequential Write** 

1700 MB/s

**Logical Blocks** 1,000,215,216

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature Features** ATA Security; TCG Opal 2.0; FIPS; TRIM; L1.2

512GB 2280 M2 SATA-3 Three Layer Cell Federal **Information Processing** Standard

**Drive Weight** 0.02 lb (10 g) Capacity 512 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm)



Interface PCIe NVMe Gen3X4

**Maximum Sequential Write** Performance **Maximum Sequential Read** 

> 530 MB/s 500 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; TCG Opal 2.0; FIPS; TRIM; L1.2

1024 GB 2280 PCIe-3x4 **NVMe TLC** 

**Drive Weight** 0.02 lb (10 g) Capacity 512 GB Height 0.14 in (3.65 mm) Width 0.87 in (22 mm)

Performance **Maximum Sequential Read Maximum Sequential Write** 

> 980 MB/s 1500 MB/s

**Logical Blocks** 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TRIM; L1.2

PCIe NVMe Gen3X4

#### **SECURITY**

**HP Fingerprint Reader** Mobile Voltage Operation 3.0V-3.6V

Interface

**Operating Temperature**  $14^{\circ} - 167^{\circ}F (-10^{\circ} - 75^{\circ}C)$ 

the Tablet)

(Optional - available on

**Current Consumption** 36 mA peak

Image

950 uA **Low Latency Wait for** 

Finger

30 cm/sec **Capture Rate** 

**ESD Resistance** IEC 61000-4-2 4B (±15KV) **Detection Matrix** 200\*1 (plus another secondary line)

508 dpi

10 mm sensor area

## **NETWORKING/COMMUNICATIONS**

#### **WWAN Modules**

## HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Technology/Operating bands LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards 3GPP Release 10 LTE Specification CAT.4, 20MHz BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9



GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)
DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)
HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps (Download), 85.6 kbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm

GPRS 900/850: 32.5 dBm

Maximum power consumption LTE: 1,200 mA (peak); 900 mA (average)

HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

**Dimensions** 42 x 30 x 2.3 mm

(Length x Width x Thickness)

\* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

## HP hs3210 HSPA+ Mobile Broadband Module\*

Technology/Operating bands HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz

E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 MHz (Band 5), 900 (Band 8) MHz

Wireless protocol standards WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9

Maximum data rates HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)

E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)

Maximum output power HSPA+: 24 dBm

E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm

Maximum power consumption HSPA+: 1,100 mA (peak); 800 mA (average)

E-GPRS: 2,800 mA (peak); 700 mA (average)

Form Factor M.2, 2242-S3 Key B

Weight 6 g

**Dimensions** 1.65 x 8.66 x 0.09 in (42 x 22 x 2.38 mm)

(Length x Width x Thickness)



\* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

#### HP lt4225 LTE/EV-DO Gobi™ 4G Mobile Broadband Module\*

Technology/Operating bands LTE: 1400 (Band 11), 800 (Band 18, Japan 800 lower)

EV-DO: 800 (BCO), 2100 (BC6) MHz

Wireless protocol standards 3GPP Release 8 LTE Specification

EVDO Release 0 and Release A

**GPS** Standalone

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 100 Mbps (Download), 50 Mbps (Upload)

CDMA 1x: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rev.A: 3.1 Mbps (Download), 1.8 Mbps (Upload)

Maximum output power LTE: 23 dBm

CDMA/EVDO: 24dBm

**Maximum power consumption** LTE: 1,200 mA (peak); 900 mA (average)

EVDO: 900mA (peak); 720mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6

**Dimensions** 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

\* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

## HP lt4226 LTE/HSPA+ Gobi 4G Module\*

Technology/Operating bands

LTE: 2100 (Band 1), 800 (Band 19, Japan 800 upper), 1450 (Band 21)

HSPA+: 2100 (Band 1), 800 (Band 6), 800 (Band 19) MHz

Wireless protocol 3GPP Release 8 LTE Specification

standards WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

**GPS** Standalone

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 100 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

HSPA+: 23.5 UBI

Maximum power Lonsumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6

**Dimensions** 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

#### HP hs3210 WW HSPA+ w/o GPS



LTE: 2100 (Band 1), 800 (Band 19, Japan 800 upper), 1450 (Band 21) Technology/Operating

bands HSPA+: 2100 (Band 1), 800 (Band 6), 800 (Band 19) MHz

Wireless protocol 3GPP Release 8 LTE Specification

standards WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification

GPS Standalone, A-GPS

**GPS** bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

LTE: 100 Mbps (Download), 50 Mbps (Upload) Maximum data rates DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)

HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

LTE: 1,200 mA (peak); 900 mA (average) Maximum power consumption HSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Key B

Weight 6 g

**Dimensions** 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

\*Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

#### **HP GPS**

Standalone GPS, GLONASS Technology

Operating bands GPS L1 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz Maximum power Active mode (continuous): 67 mA (peak); 26 mA (average) consumption

M.2, 3042-S3 Key B Form Factor

Weight 4.3 g

**Dimensions** 42 x 30 x 2.3 mm

Interoperability

**Frequency Band** 

(Length x Width x Thickness)

## **WLAN MODULES**

## Intel® Dual band wireless-AC 8265 802.11AC 2x2 WiFi + BT 4.2 Combo Adaptor (non-vPro™)

Wireless LAN IEEE 802.11a **Standards** IEEE 802.11b

IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi certified 802.11b/g/n

2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully



comply with requirements of 15.247 or otherwise disable those channels.

#### 802.11a/n

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note: Indonesia no support this band)

#### **Data Rates**

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

#### Modulation

**Direct Sequence Spread Spectrum** 

#### Security<sup>1</sup>

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

- IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

### **Network Architecture** Models

Roaming

Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points

#### Output Power<sup>2</sup>

- 802.11b: +16dBm minimum
- 802.11g: +14dBm minimum
- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +14dBm minimum
- 802.11n HT40(2.4GHz): +12dBm
  - minimum
- 802.11n HT20(5GHz): +14dBm minimum
- 802.11n HT40(5GHz): +12dBm minimum

## **Power Consumption**

2.0 W (max) Transmit: 1.6 W (max) Receive:

Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated)



Connect Standby: 10 mW (WLAN+BT)

Radio disabled: 5 mW

**Power Management** ACPI and PCI Express compliant power

management

802.11 compliant power saving mode Receiver Sensitivity<sup>3</sup> 802.11b, 1Mbps: -94dBm maximum

Receiver Sensitivity<sup>3</sup> 802.11b, 1Mbps : -94dBm maximum 802.11b, 11Mbps : -86dBm maximum

802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum

802.11ac, 1SS, MCS-9: -61dBm maximum 802.11ac, 2SS, MCS-0: -83dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum High efficiency antenna with spatial diversity,

Antenna type High efficiency antenna with spatia mounted in the display enclosure

Two embedded dual band 2.4/5 GHz antennas are

provided to the card to support WLAN MIMO communications and Bluetooth communications

 Form Factor
 PCI-Express M.2 MiniCard

 Dimensions
 Type 2230: 2.3 x 22.0 x 30.0 mm

0r

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

Or

Type 1630: 2g

Operating Voltage 3.3v +/- 9%

Altitude

 Temperature
 Operating Non-operating
 14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)

 Humidity
 Operating
 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing) Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)
LED Activity LED Amber – Radio OFF; LED White – Radio ON

- Check latest software/driver release for updates on supported security features.
- Maximum output power may vary by country according to local regulations.
- Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant
Frequency Band 2402 to 2480 MHz
Number of Available Channels Legacy: 0~79 (1 MHz/CH)
BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels



0.001% BER

## **Technical Specifications**

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 4 dBm for BR and EDR.

**Receiver Sensitivity** 

Modulation 0.01% BER Legacy GFSK -80 dBm -80 dBm

-70 dBm π/4-DQPSK -70 dBm 8DPSK -80 dBm -70 dBm

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW

USB 2.0 compliant

Selective Suspend 17 mW Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m)

**Electrical Interface** 

**Bluetooth Software Supported** 

**Link Topology** 

**Electrical Interface** 

**Bluetooth Software Supported** 

Security

Range

Microsoft Windows Bluetooth Software

Point to Point, Multipoint Pico Nets up to 7 slaves

Full support of Bluetooth Security Provisions **Power Management** Microsoft Windows ACPI, and USB Bus Support

Certifications

Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff

All necessary regulatory approvals for supported countries, including: Security

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Bluetooth Profiles Supported** 

**Power Management** Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark Serial Port Profile (SPP)1

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)1,2

Certifications

**Bluetooth Profiles Supported** 

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)1,2

Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)

Bluetooth V4.1/V4.2 support V4.1: ESR5/6/7 compliant

feature

V4.2: ESR8 compliant, LE Secure Connection - Basic.

\* Wireless access point and Internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

Intel® Dual band wireless-AC 8265 802.11AC 2x2 WiFi + BT 4.2 Combo Adaptor (VPro)



**Frequency Band** 

**Wireless LAN** IEEE 802.11a IEEE 802.11b **Standards** IEEE 802.11g IEEE 802.11n IEEE 802.11ac Interoperability Wi-Fi certified

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

## 802.11a/n

802.11b/g/n

- 4.9 4.95 GHz (Japan)
- 5.15 5.25 GHz
- 5.25 5.35 GHz
- 5.47 5.725 GHz
- 5.825 5.850 GHz

Note: Indonesia no support this band)

#### **Data Rates**

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

## Modulation

**Direct Sequence Spread Spectrum** 

## Security<sup>1</sup>

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM IEEE and WiFi compliant 64 / 128 bit WEP

- encryption for a/b/g mode only AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK. TKIP. and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

#### **Network Architecture** Models Roaming

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access

points Output Power<sup>2</sup>

802.11b: +16dBm minimum

802.11g: +14dBm minimum



- 802.11a: +14dBm minimum
   802.11n HT20(2.4GHz): +14dBm
- 802.11n HT40(2.4GHz): +12dBm minimum
- 802.11n HT20(5GHz): +14dBm minimum
   802.11n HT40(5GHz): +12dBm minimum
- Power Consumption Transmit: 2.0 W (max) Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)

Connect Standby: 10 mW (WLAN+BT)
Radio disabled: 5 mW

**Power Management** ACPI and PCI Express compliant power

management

802.11 compliant power saving mode Receiver Sensitivity<sup>3</sup> 802.11b, 1Mbps: -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 2SS, MCS-0: -83dBm maximum 802.11ac, 2SS, MCS-0: -83dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna type High efficiency antenna with spatial diversity,

mounted in the display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

0r

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

Altitude

 Temperature
 Operating Non-operating
 14° to 158° F (-10° to 70° C)

 Humidity
 -40° to 176° F (-40° to 80° C)

 10% to 90% (non-condensing)

 Operating
 10% to 90% (non-condensing)

 Non-operating
 5% to 95% (non-condensing)

 Operating
 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)
LED Activity LED Amber – Radio OFF; LED White – Radio ON

- Check latest software/driver release for updates on supported security features.
- Maximum output power may vary by country according to local regulations.



3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

**Bluetooth Specification** 4.0/4.1/4.2 Compliant 2402 to 2480 MHz **Frequency Band Number of Available Channels** Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth device

with a maximum transmit power of + 4 dBm for BR and EDR.

**Receiver Sensitivity** 0.01% BER 0.001% BER Modulation Legacy **GFSK** -80 dBm -70 dBm

π/4-DQPSK -80 dBm -70 dBm 8DPSK -80 dBm -70 dBm

**Power Consumption** Peak (Tx) 330 mW

Peak (Rx) 230 mW Selective Suspend 17 mW Legacy Up to 33 ft (10 m)

Range BLE Up to 99 ft (30 m) USB 2.0 compliant

**Electrical Interface** 

**Bluetooth Software Supported Link Topology** 

**Electrical Interface** 

**Bluetooth Software Supported** 

Security

Point to Point, Multipoint Pico Nets up to 7 slaves

Full support of Bluetooth Security Provisions

Microsoft Windows Bluetooth Software

Microsoft Windows ACPI, and USB Bus Support **Power Management** Certifications

Self-configurable to optimize power conservation in all operating

modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries, including:

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Bluetooth Profiles Supported** 

ETS 300 328, ETS 300 826 **Power Management** Certifications Low Voltage Directive IEC950 UL, CSA, and CE Mark

Serial Port Profile (SPP)1

Service Discovery Application Profile (SDAP)

Certifications Dial-Up Networking (DUN)1,2

**Bluetooth Profiles Supported** Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)1,2

Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2



Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)

Bluetooth V4.1/V4.2 support

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feature

V4.2: ESR8 compliant, LE Secure Connection – Basic

\* Wireless access point and Internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

#### **POWER**

HP 45 W USB Type-C™ AC Dimensions

adapter

62.0x62.0x28.5mm Weight unit: 220g +/- 10g Input

**Input Efficiency** 

Average Efficiency of 25%, 50%, 75%, 100% load

condition with 115Vac/230Vac Spec:

5V:81.5% 9V:86.7% 10V:87.5% 12V:87.8% 15V:87.8% 20V:87.8%

Input frequency range

47 ~ 63 Hz **Input AC current** Max. 1.4 A at 90 Vac

Output **Output power** 

5V/15W 9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

DC output

5V/9V/10V/12V/15V/20V

Hold-up time 5ms at 115 Vac input **Output current limit** 

<5.0A

USB Type-C Connector

Operating temperature **Environmental Design** 

32oFto 95oF (0oto 35oC)

Non-operating (storage) temperature

-4oFto 185oF (-20oto 85oC)

Altitude

0 to 16,400 ft (0 to 5000m)

Humidity



20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Certifications .

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency

approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B,

CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65 W USB Type-C™ AC Dimensions

adapter

Weight

unit: 245g +/- 10g Input

Input Efficiency

74x74x28.5mm

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @

15V/4.33A 89% min at 115 Vac/ 230Vac @

20V/3.25A

Input frequency range

47 ~ 63 Hz

Input AC current

1.7 A at 90 VAC and maximum load

Output **Output power** 

65W

DC output

5V/9V/10V/12V/15V/20V

Hold-up time 5ms at 115 Vac input **Output current limit** 

<8.0A

Connector USB Type C

**Environmental Design** Operating temperature

32oFto 95oF (0oto 35oC)

Non-operating (storage) temperature

-4oFto 185oF (-20oto 85oC)

Altitude

0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95%

**Storage Humidity** 5% to 95%

**EMI and Safety** Certifications

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.



\* MTBF - over 100,000 hours at 25°C ambient condition.

HP 4-cell Polymer Battery (47 WHr)

**Dimensions (H x W x L)** 4.46 x 265.6 x 81.15 mm

0.18 x 10.45 x 3.2 inch

 Weight
 0.195 kg/0.88 lb

 Cells/Type
 Li-ion/Polymer cell

 Energy
 Voltage: 7.7V

Amp-hour capacity: 6.11Ah Watt-hour capacity: 47 WHr

Watt-hour capacity

Temperature Operating (Charging)

 Operating (Charging)
 32° to 113° F (0° to 45° C)

 Operating (Discharging)
 14° to 140° F (-10° to 60° C)

 Non-operating
 -4° to 140° F (-20° to 60° C)

Battery recharge time System in OFF or Standby

Mode <3 hours

Fuel Gauge LED No

Optional travel No battery available

## **COUNTRY OF ORGIN**

China



## **CLEANING**

The following cleaning solutions, if used as instructed in the user guide, will not harm the surface of the HP Elite x2 1012 G2 Collaboration Keyboard:

- Alcohol-free glass-cleaning fluid
- Solution of mild soap and water
- Dry microfiber cleaning cloth or a chamois (static-free cloth without oil)
- Static-free cloth wipes

Please refer to the user guide that came with your product for detailed instructions about how to clean your HP Elite x2 1012 G2 using these solutions.

The following cleaning solutions, if used as instructed in the user guide, will not harm the surface of HP Elite x2 1012 Travel Keyboard and the HP Elite x2 1012 Advanced Keyboard:

Surface side of the keyboards:

- Alcohol-free glass-cleaning fluid
- Solution of mild soap and water
- Dry microfiber cleaning cloth or a chamois (static-free cloth without oil)
- Static-free cloth wipes



Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part number
Cases	HP Elite Top Load Colombian Leather Case	Т9Н72АА
	HP Elite Top Load Herringbone Nylon Case	Т9Н7ЗАА
	HP Elite x2 1012 G2 Protective Case	1HM07AA
Docking	HP Elite 90W Thunderbolt 3 Dock	1DT93AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Travel HUB	Z9G82AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock Non Flash	3DV65AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock w/Combo Cable	3TR87AA
	HP Thunderbolt Dock 120W w/ Audio	3YE87AA
	HP Thunderbolt Audio Module	3AQ21AA
	HP USB-C Mini Dock	1PM64AA
	HP USB-C Travel Hub	Z9G82AA
Input Devices	HP Elite x2 1012 G2 Collaboration Keyboard	1FV39A
	HP Active Pen with Bluetooth App Launch Button	T4Z24AA
	HP USB Type-C to VGA Adapter	N9K76AA
	HP USB Type-C to HDMI Adapter	N9K77AA
	HP USB Type-C to DisplayPort Adapter	N9K78AA
	HP USB Type-C to Gigabit Ethernet Adapter	V8Y76AA
Power	HP 45W USB-C Auto Adapter	Z3Q87AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA



## QuickSpecs

**HP Elite x2 1012 G2** 

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# QuickSpecs

HP Elite x2 1012 G2

**Summary of Changes** 

